

IN THE ABSTRACT

Please amend the Abstract as follows.

Abstract of the Disclosure

A semiconductor integrated circuit device ~~comprises~~ has a semiconductor substrate ~~with squared in plane surface,~~ a plurality of pads disposed over a main surface of the ~~semiconductor substrate along one side thereof of the semiconductor substrate,~~ a. A plurality of input/output cells are disposed corresponding to the plural pads over the main surface of the ~~semiconductor substrate.~~ An, ~~an~~ internal circuit forming section is disposed over the main surface of the ~~semiconductor substrate, and inner than the plural input/output cells, and power~~ Power supply wirings for the internal circuit, ~~for supplying~~ supply potentials to the internal circuit forming section, ~~which are respectively disposed inner than the plural input/output cells.~~ The plural input/output cells include signal cells and power supply cells for internal circuit respectively. ~~The plural pads include signal pads respectively~~ Signal pads are disposed corresponding to the signal cells and electrically connected to the signal cells. Power, ~~and power~~ supply pads for the internal circuit are respectively disposed corresponding to the power supply cells and electrically connected to the power supply cells and the power supply wirings. ~~The power supply~~

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~~pads are disposed closer to the power supply wirings than the
signal pads.~~